

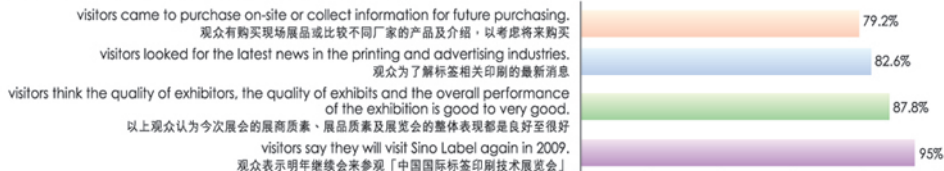
## Sino-Label 08 Expanded in Leaps 08展会规模再创新高

Renowned exhibitors including AVT(Brotech) · Mark Andy, Lintec, Avery Dennison, Avery Dennison Printer System, Pantone, Labelmen, Wutung, ETI, Sanki, ITW ,TaiYo, Wanan, Zhonglian, Haolian, Gold Fai, H. Shine, Colamark, Faxinzhongxin, Zhongshan Fuzhou, King Label, Lecco, KK-Tack etc. displayed the latest label printing technologies, equipment and materials, etc. Sino Label 2008 built a very successful business and technology exchange platform for the label printing industry.

<中国国际标签印刷工业展览会>2008 集合了标签行业领先企业的盛会，知名展商如：博泰(以色列AVT)、联合印刷(Mark Andy)、日本琳得利、艾利、艾利丹尼森、彩通、罗铁、互通多威龙、加拿大ETI、日本三起、美国ITW、新冈太阳、台湾万诺、中天、浩田、金辉、冯太祥、达尔嘉、法鑫思信、中山富洲、金利宝、联冠、高冠等，全面展示了标签印刷业最新技术及产品，打造高水准的商贸及交流平台。

**Total Number of Visitors (PPF) 观众总数目：41,692 trade visitors 业内观众**  
**Visitors from Overseas 海外观众数目：6,713**

### Visitor Statistics of Sino Label 08 上届观众数据统计：



## Concurrent Symposia 同期研讨会

- ◆ Symposium on Labeling and Packaging Technology for Daily Chemical Products  
日化产品标签与包装技术研讨会
- ◆ Symposium on Labeling and Packaging Technology for Food Products  
食品标签与包装技术研讨会
- ◆ Co-organized by the Label Printing Sub-Council, China Trade Association for Anti-Counterfeiting; and 《Labels and Labeling》 magazine, and supported by The Standardization Association of Guangdong Province, a total of 156 influential high quality audience people attended the two symposia held on March 5, 2008.  
由中国防伪行业协会不干胶印制分会及《中国标签与贴标》协办，广东省标准化协会支持，156位业内听众参加了于2008年3月5日举行的两场研讨会。
- ◆ Topics of the symposia covered such things as the development trends of the global labeling market; opportunities & challenges in the China market; the standards for labeling and packaging of daily chemical and food products in Europe and America; technology and applications in smart labels, flexo printing, total coding, inkjet digital printing; 100% automation inspection technology, application of label materials; and in-mold labeling technology.  
议题包括全球标签市场发展趋势与我国标签市场面临的机遇与挑战；欧美国食品/日化产品标签与包装标准采购；智能标签、柔版印刷、全面标识、喷墨数字印刷等技术在包装中的应用、100%自动检测技术、标签材料的应用及模内贴标技术等多方面议题。

